Product Overview

SK-AM62-SIP Design Package Folder and Files List

Table 1 lists names of the folders and file names in the folders along with the format for all the files that have been included in the SK-AM62-SIP. The SK-AM62-SIP starter kit (SK) evaluation module (EVM) is a stand-alone test and development platform built around the AM6254 system-on-a-chip (SoC) with integrated 512 MB LPDDR4 SDRAM in a single package. AM625SIP processors are comprised of a quad-core 64-bit Arm®-Cortex®-A53 microprocessor and single-core Arm Cortex-M4F MCU. The product overview document is available on SK-AM62-SIP product folder on TI.com for customers to review before downloading the single Zip folder.

Table 1. PROC162E1

FOLDER (1st Level)	FOLDER (2nd Level)	Files Inside	File Type
----	----	PROC162E1_Folders_Files_List	XLS
		2024 Important Notice	PDF
1_SCHEMATIC	PDF	PROC162E1_Sch_With_Design_Updates..Notes_V1.0	
	PDF -Backup_SK_Schematic	PROC162E1_sch	PDF
	----	Proc162E1_Schematic_Revision_Readme	PDF
	ORCAD	PROC162E1_Sch_With_Design_Updates..Notes_V1.0	DSN
	ORCAD - Backup_SK_Schematic	PROC162E1_SCH	DSN
2_BOM	----	PROC162E1_BOM_With_Design_Updates..Notes_V1.0	XLS
	Backup_SK_Schematic_BOM	PROC162E1_BOM	XLS
3_Board_File	Allegro	PROC162E1_BRD	BRD
	Simulation Scorecard	AM62x_Simulation_Scorecard	PDF
	Altium_ASCII	PROC162E1_BRD	ALG
4_Gerber	ODBGBR	PROC162E1_ODBGBR	ZIP
	274X	PROC162E1_274xGBR	ZIP
	IPC-D-356_NETLIST	PROC162E1_BRD	IPC
5_Gerber_PDF	FAB	PROC162E1_FAB	PDF
	PCB LAYERS	PROC162E1-LAYERS	PDF
	Geber Layers	PROC162E1-LAYERS	PDF
6_Assembly_Models_Package	2D	PROC162E1_BASY	DXF
		PROC162E1_TASY	DXF
	3D	PROC162E1_3D_STEP	STP
	IDF	PROC162E1_BRD	EMP
		PROC162E1_BRD	EMN
	Assembly_Drawing_PDF	PROC162E1_ASSEMBLY	PDF
		PROC162E1_TASY	PDF
		PROC162E1_BASY	PDF
	STNL	art_aper + 8 x .ART files	ART
	XY-REP	PROC162E1_XY-REP	XLS
7_PCB_LAYER_STACKUP	---	SK-AM62-SIP_PROC162E1_Layer_STACKUP	PDF

References

- Texas Instruments, *[FAQ] AM625SIP - Custom board hardware design - Design and Review notes for Reuse of SK-AM62-SIP Schematics* article

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